



Shenzhen Flourish Electronics Co., LTD

FILE NO.

QC-T4-09

Ver:

1.0

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(C) D- C

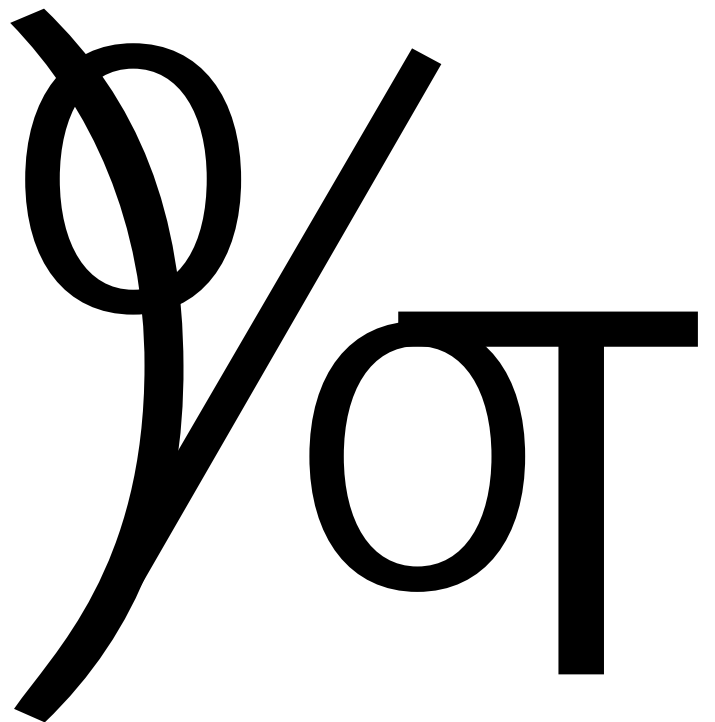


CUSTOMER

PART NO

DESCRIPTION

6 T P





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		SEC CHECK	RELEASE DATE
1.0	CHECKED AND RELEASED		2022/06/01



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: -40 ~175

: -10 ~40



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FB

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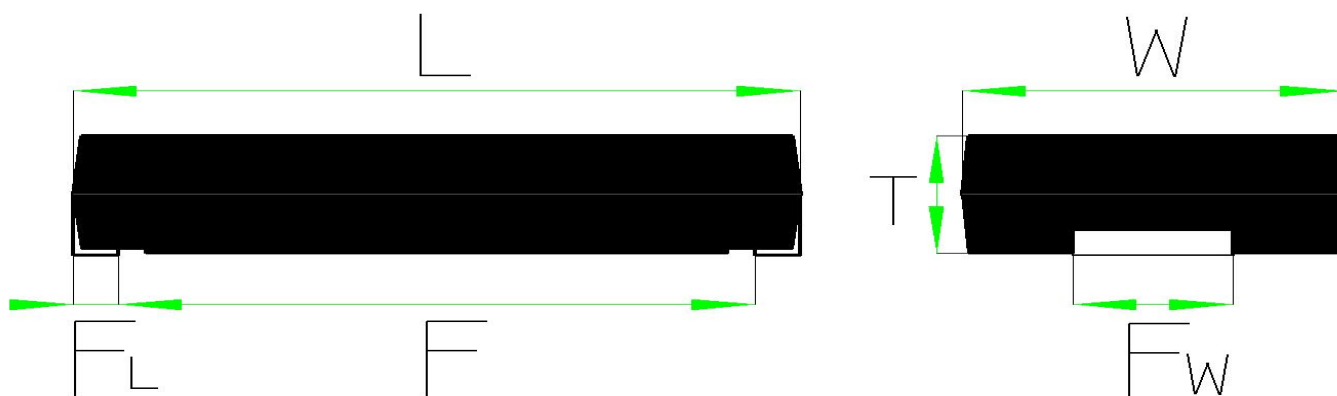
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2.1

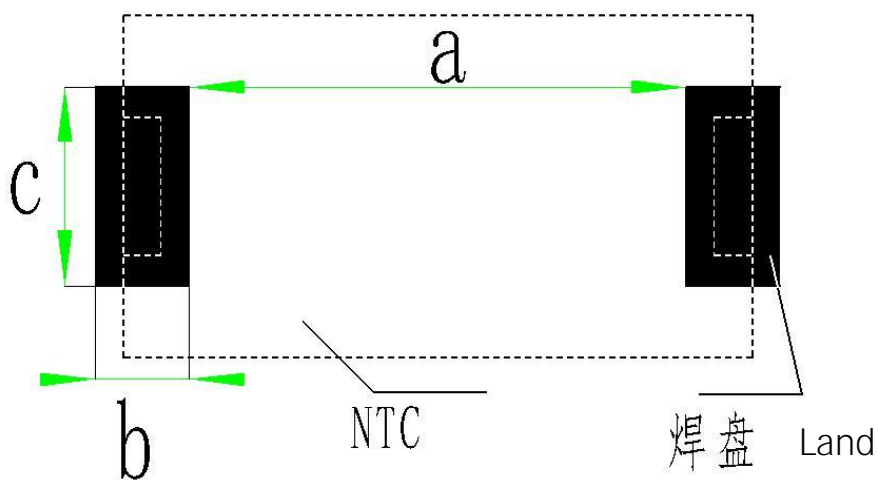
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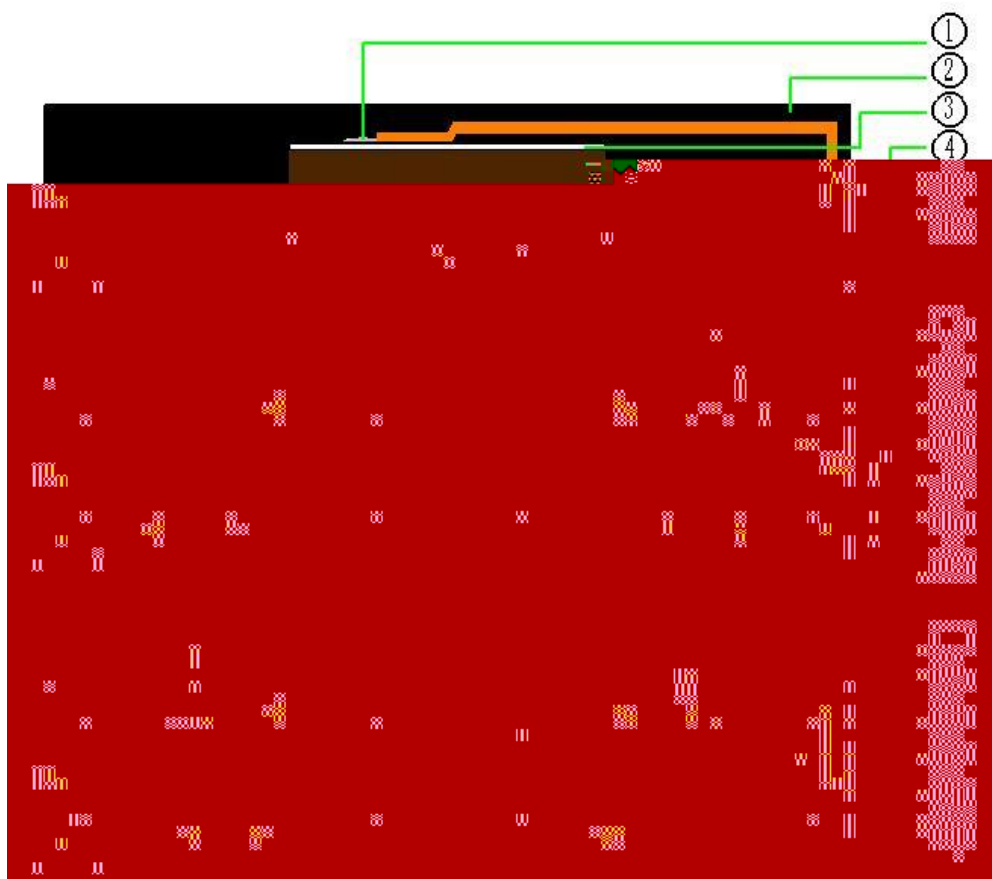
2.2 : mm



	±	±	±	±	±	±

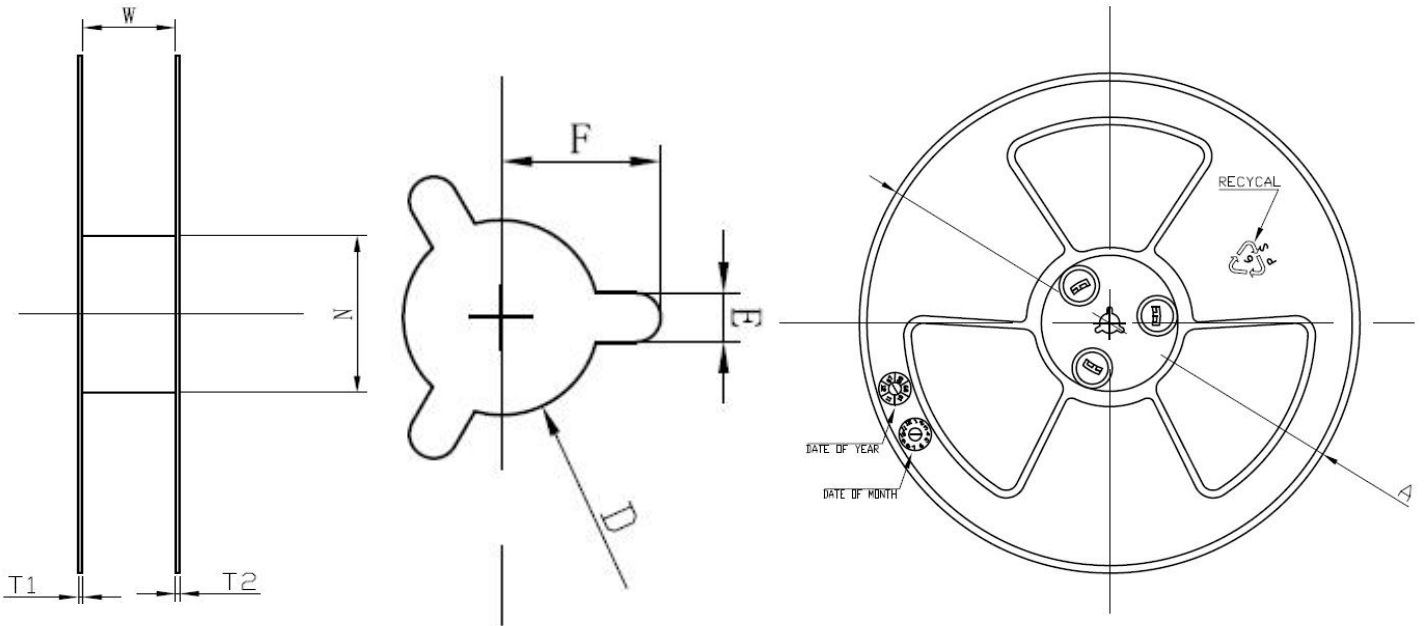
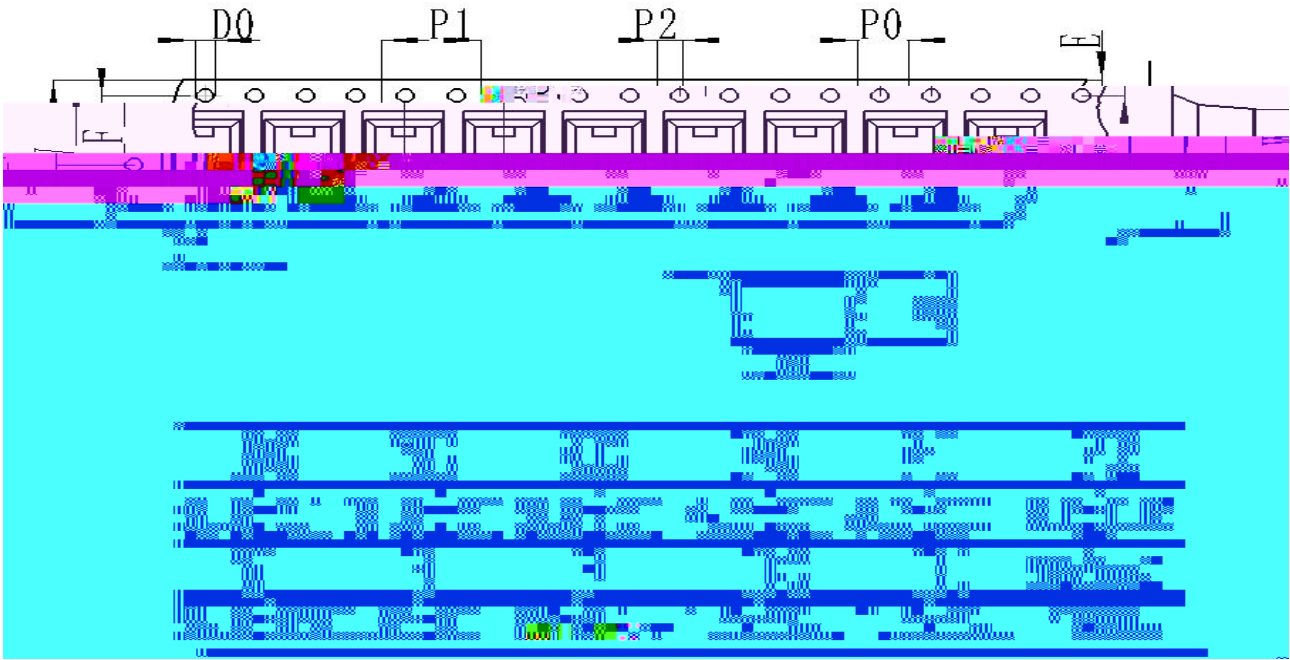
2.3 : mm



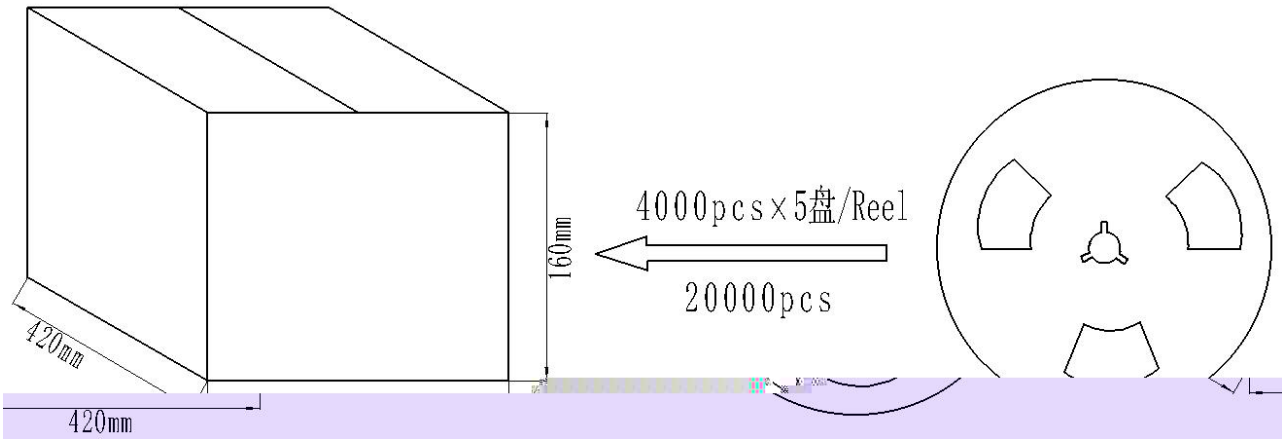


No.	Part name	Material	RoSH
1		Sn-Sb /Sn-Pb-Ag	RoSH
2		UL94V-0	
3		/	
4			
5			
6	SMD		

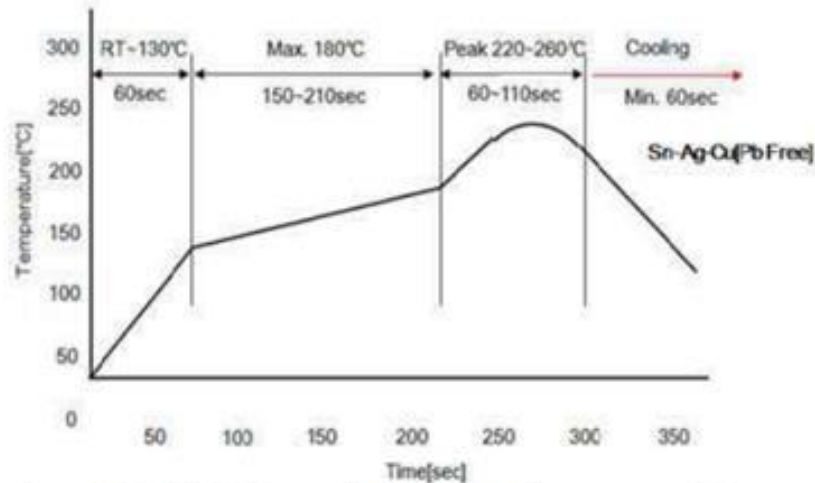
1



	±	±	±	±	±	±	±	±



☆ 回流焊接曲线



温区	温度范围 (°C)	时间 (sec)	备注
a	RT~130	60	焊锡: Sn-Ag-Cu 高温时间: < 10 sec
b	180 max	150~210	
c	220~260(260 max)	60~110	
d	220~RT	60 min	

当焊接温度低于锡的熔点时，贴片镀锡端子的可焊性将下降。使用之前请确认贴片镀锡电极的可焊性。焊接区出风口及内部空间最高温度不能超过 280°C，温度超过时，会造成产品发生失效。由于超温使用所造成的不良，我司不予承担责任。



NTC

NTC

MSL3

6

:10to30

:60%max.

168

HIC

6

HIC

60 *168hr.

()

Level	Bake@40C 5%RH	
	Saturated@30C/85%RH	At limit of Floor life+7@30C 80RH
	7days	6days

()

1

NTC

NTC

2

PCB/PWB

NTC

NTC

: 400C

: 50W

: 3.5



3

NTC

() /

4

(100C)

()

:

: 20W

: 5

PCB/PWB